PTO/SB/08 Equivalent

## INFORMATION DISO OSUB-

(Multiple sheets used when necessary)
SHEET 1 OF 1

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Application No.	10/797,888
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First Named Inventor	Paraschiv, Vasil·
Art Unit	1765
Examiner	Vinh, Lan
Attorney Docket No.	IMEC312.001AUS

U.S. PATENT DOCUMENTS							
Examiner Initials	Cite No.	Document Number Number - Kind Code (if known) Example: 1,234,567 B1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear		
LV	1	2003/109106 a1	06/12/2003	Pacheco Rotondaro Antonio Luis, et al.			
ĽV	2	5,271,797 a	12/21/1993	Kamisawa et al.			
ΓΛ	3	4,087,367	05/02/1978	Rioult et al.			

FOREIGN PATENT DOCUMENTS						
Examiner Initials	Cite No.	Foreign Patent Document Country Code-Number-Kind Code Example: JP 1234567 A1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear	T <sup>1</sup>
ΓΛ	4	EP 0 968 979 A	01/05/2000	Siemens Aktiengesellschaft		

NON PATENT LITERATURE DOCUMENTS				
Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>1</sup>	
LV	5	WATANABE D, et al., Selective Wet Etching for High-K Material by Organic Solvent Containing Hydrofluoric Acid", Semiconductor Pur Water and Chemicals Conference, 02/17/2003, pp. 117-130, XP008057967.		
LV	6	CHRISTENSON, K. Selective Wet Etching of High-K Materials, Solid State Technology Online, 07/03/2003 pp. 1-7, XP002361400.		
LV	7	European Search Report for related European Application No. EP 04447059.9, mailed on February 8, 2006.		

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Examiner Signature /Lan Vinh/ Date Considered 07/06/2006

<sup>\*</sup>Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

T<sup>1</sup> - Place a check mark in this area when an English language Translation is attached.